Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	100	V
Emitter-Base Voltage	V_{EBO}	6	V
Continuous Collector Current	I_C	3	A
Peak Pulse Collector Current	I_{CM}	5	A
Continuous Base Current	I_B	1	A
Power Dissipation	P_D	15	W

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

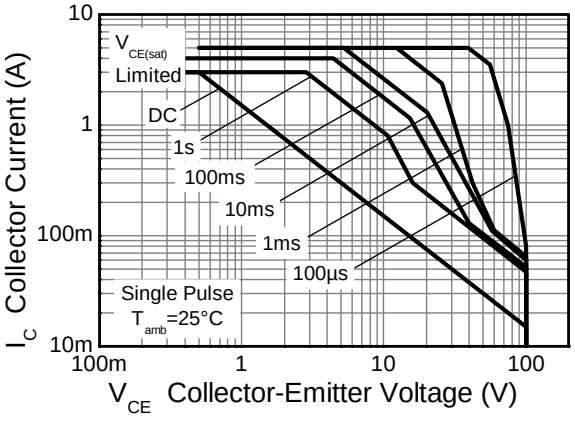
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P_D	3.9	W
	(Note 7)		2.1	
	(Note 8)		1.6	
Thermal Resistance, Junction to Ambient Air	(Note 6)	$R_{\theta JA}$	32	°C/W
	(Note 7)		59	
	(Note 8)		80	
Thermal Resistance, Junction to Leads	(Note 9)	$R_{\theta JL}$	8.4	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 10)

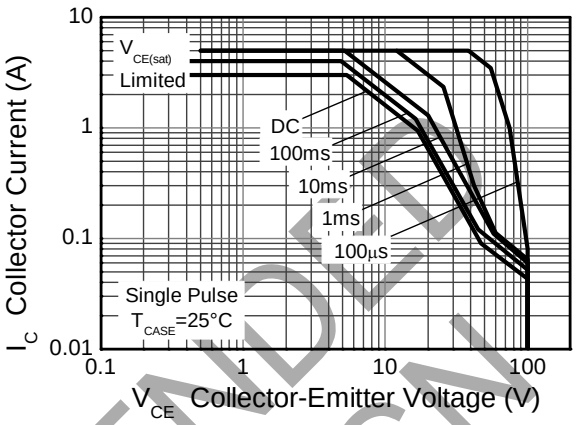
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:
6. For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
7. Same as note (6), except mounted on 25mm x 25mm 1oz copper.
8. Same as note (6), except mounted on minimum recommended pad (MRP) layout.
9. Thermal resistance from junction to solder-point (on the exposed collector pad).
10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

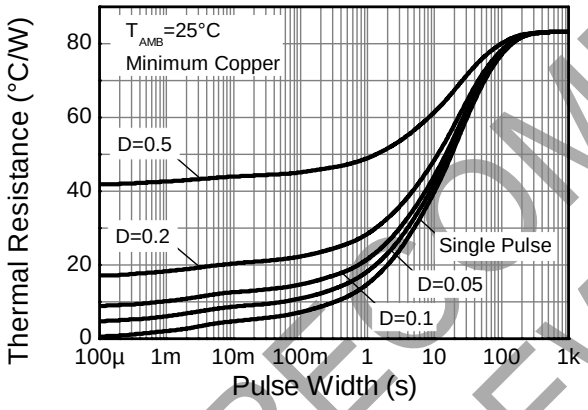
Thermal Characteristics



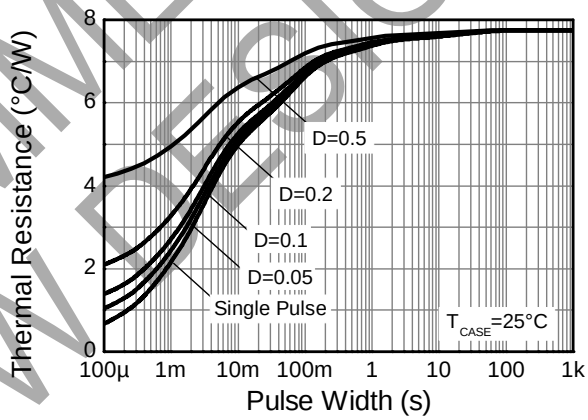
Safe Operating Area



Safe Operating Area



Transient Thermal Impedance



Transient Thermal Impedance

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 11)	BV_{CEO}	100	—	—	V	I_C = 30mA, I_B = 0
Collector Cut-off Current	I_{CEO}	—	—	1	μA	V_{CB} = 60V, I_B = 0
Collector Cut-off Current	I_{CES}	—	—	1	μA	V_{CE} = 100V, V_{EB} = 0
Emitter Cut-off Current	I_{EBO}	—	—	1	μA	V_{EB} = 5V, I_C = 0
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	—	—	1.2	V	I_C = 3.0A, I_B = 375mA
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	—	—	1.8	V	I_C = 3A, V_{CE} = 4V
DC Current Gain (Note 11)	h_{FE}	25 10	—	— 50	—	V_{CE} = 4V, I_C = 1A V_{CE} = 4V, I_C = 3A
Current Signal Current Gain	H_{fe}	20	—	—	—	V_{CE} = 10V, I_C = 0.5A, f = 1KHz
Current Gain-Bandwidth Product	f_T	3.0	—	—	MHz	I_C = 500mA, V_{CE} = 10V, f = 1MHz

Note: 11. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

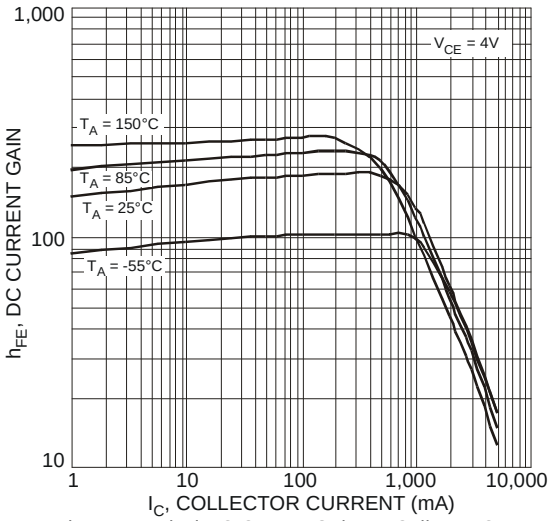


Figure 1 Typical DC Current Gain vs. Collector Current

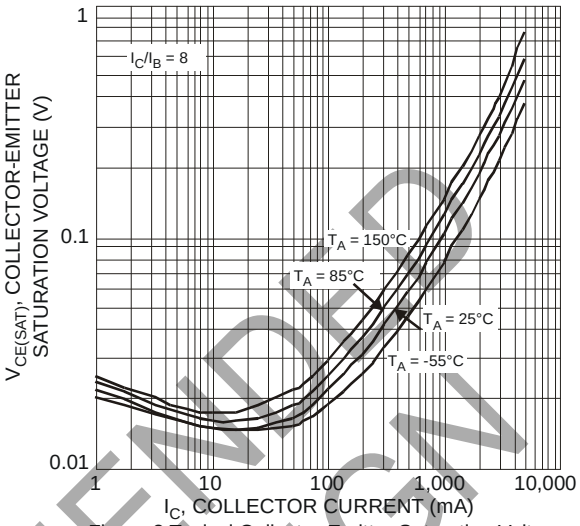


Figure 2 Typical Collector-Emitter Saturation Voltage vs. Collector Current

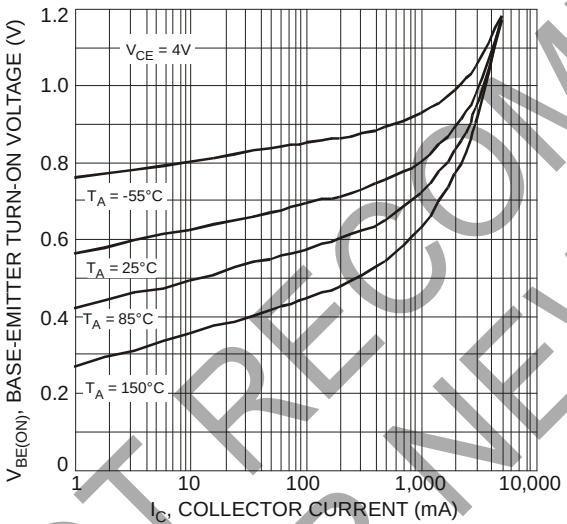


Figure 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

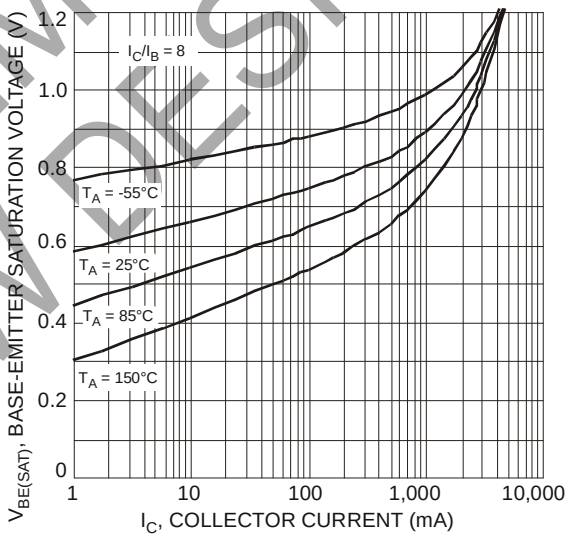


Figure 4 Typical Base-Emitter Saturation Voltage vs. Collector Current

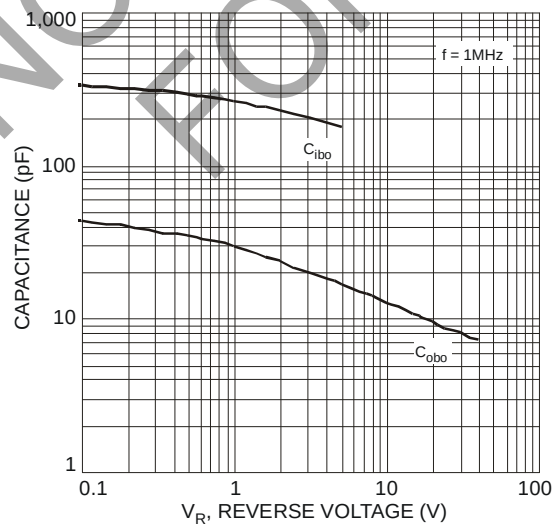
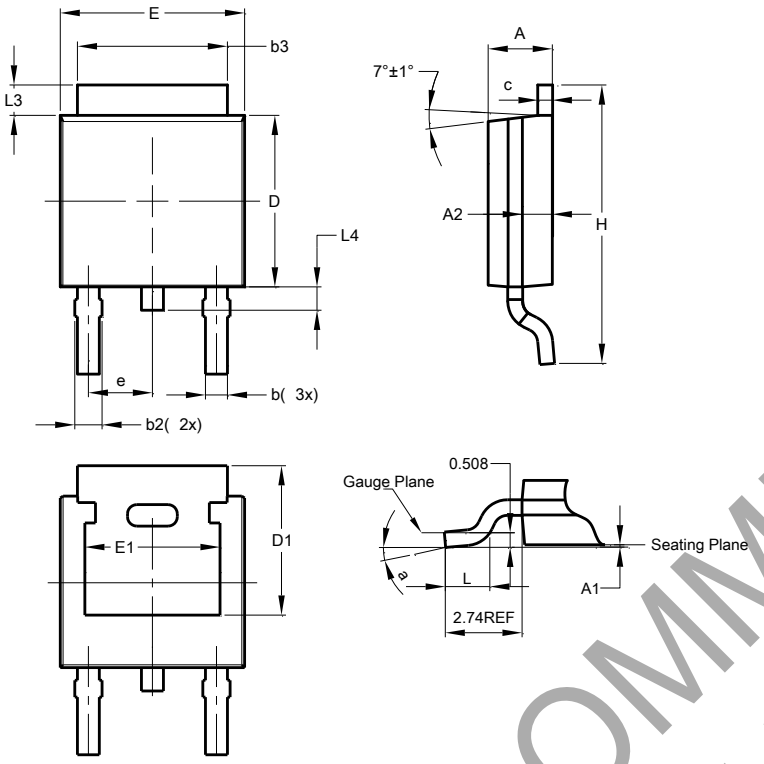


Figure 5 Typical Capacitance Characteristics

Package Outline Dimensions

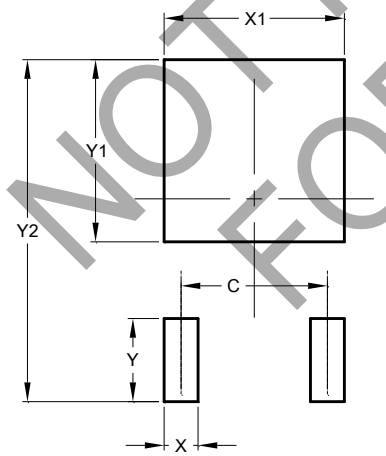
Please see http://www.diodes.com/package-outlines.html for the latest version.



TO252 (DPAK)			
Dim	**Min**	**Max**	**Typ**
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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